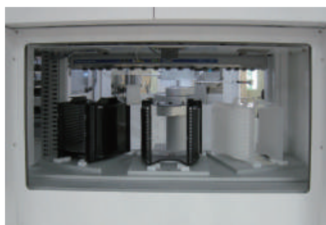
WAFER BONDING SYSTEM

HBS-800A Series
Full Automation

Optimized equipment for mass-production for wider 8 inch wafer Full Automation equipment with combined unit of Stacker and Aligner (PRE+FINE)

Application:

MicroLED, MiniLED, FBAR Filter, SAW Filter, CMOS Image Sensor, MEMS, Semiconductor, Acceleration Sensor, Vertical LED



CASSETTE

STACKER

ALIGNER

PM

FEATURE	WAFER SIZE		8 Inch (Option 12 Inch)
	WAFER		Si, Sapphire, GaAs, and so on.
	BONDING METHOD		Eutectic,Thermo Compressive Standard
	TYPE		Full Automation
MAIN MODULE	EFEM MODULE TRANSFER ROBOT MODULE STACKER MODULE PRE ALIGNER & FINEALIGNER MODULE PROCESS MODULE (MAX 4 MODULE ADD) – CHAMBER, PRESS, HEATING, VACUUM PUMP		
DIMENSION (W x D x H)	WAFER BONDER		2500 x 2500 x 2000 mm
	CONTROL BOX		2000 x 900 x 2000 mm
	VACUUM PUMP		477 x 925 x 839 mm
EFEM	EFEM		CST REGISTER
	UNLOADING		BONDED CST
	CST REGISTER		BAR CODE READ
TR (Transfer Robot)	WAFER SIZE		8 Inch (Option 12, 6 Inch)
	ARM		DUAL (WAFER / JIG)
	MAPPING		AUTO DETECTING
	DRIVING		3 AXIS (X, T, Z)
STACKER	WAFER SIZE		8 Inch (Option 12, 6 Inch)
	ACCOMMODATION		4 JIG STANDARD (MAX 8 JIG OPTION)
	MOVING		UP / DOWN ELEVATION
	COOLING		COOLING STATION (BY WATER)
ALIGNER (PRE+FINE)	ALIGN STAGE		4 AXIS MOVING
	CAMERA STAGE		2 AXIS MOVING
	ACCURACY		±50um
	TYPE		VISION (FLAT ZONE & NOTCH)
PM (Process Module)	HEATING	TEMP	MAX. 400˚C (OPTION 500˚C)
		UNIFORMITY	RAMP : ≤±3%
			DWELL : ≤±1.5%
			COOL : ≤±3%
	PRESSURE	FORCE	MAX 70kN
		UNIFORMITY	≤SETTING PARAMETER±3%
		ACCURACY	≤SETTING PARAMETER±1%
	CHAMBER		N2 + WATER COOLING
	VACUUM		MAX.30mmTorr